



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	Tae Heon Lee et al.	)	Confirmation No.	8528
		)		
Serial No.:	10/763,859	)	Art Unit:	2814
		)		
Filed:	01/23/2004	)	Examiner:	Cao, Phat X.
		)		
For:	Semiconductor Package Having	)		
	Reduced Thickness	)		

**AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Restriction Requirement mailed March 21, 2005 in relation to the above-identified divisional patent application, please amend the application as follows: